



Product Change Notification

Change Notification #: 118620-00
Change Title: Select Intel® RAID Module RMSP3HD080E, Intel® Storage Module RMSP3JD160J, PCN 118620-00, Product Discontinuance, End of life
Date of Publication: October 25, 2021

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins	October 25, 2021
Last Product Discontinuance Order Date	April 29, 2022
Orders are Non-Cancelable and Non-Returnable After	February 28, 2022
Last Product Discontinuance Shipment Date	April 28, 2023

Description of Change to the Customer:

The Intel SKUs listed in the products affected table will End of life

Customer Impact of Change and Recommended Action:

Determine your remaining demand for this product and order accordingly. Intel reserves the right to extend the Last Product Discontinuance Shipment Date based on manufacturing capabilities and supply availability.

The recommended replacement SKUs are noted within the affected products table within this PCN notice but Intel recommends contacting your local Intel Field Sales Representative as form factor may be different and additional options will be available later.

Please contact your local Intel Field Sales Representative if you have any further questions about the product transition or End of Life process.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	Affected MM#	Recommended replacement Product Code	Recommended replacement MM#
Intel® Storage Module RMSP3JD160J, 5 Pack	RMSP3JD160J	954490	RS3P4QF160J	999RKM
Intel® RAID Module RMSP3HD080E, 5 Pack	RMSP3HD080E	954553	RS3P4TF160F	999TJ4

PCN Revision History:

Date of Revision:

October 25, 2021

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

118620-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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